

APPROVAL SHEET

MULTILAYER CHIP VARISTOR

For Surge Protection

Size 0603

VZ0603 Green Material Series

*Contents in this sheet are subject to change without prior notice.



DESCRIPTION

Walsin Multilayer Chip Varistor is a family of Transient Voltage Surge Suppression products. Today, electronic circuits are becoming smaller and more sentive to external interference. Walsin Multilayer Chip Varistor is designed to protect components from destruction of transients and ESD(Electronic Static Discharge). The wide operating voltage and energy rage make Walsin Multilayer Chip Varistor suitable for numerous applications on I/O protection, Vcc protection, Keyboard protection, LCD protection, Sensor protection...etc. The Walsin Chip Varistor is manufactured by Multilayer fabrication technology providing excellent voltage clamping ability and is supplied in leadless, surface mount form, compatible with modern reflow and wave soldering procedures.

FEATURES

- 1. Multilayer fabrication technology
- 2. -55°C to 125°C operating temperature Range
- 3. Operating voltage range $V_{M(DC)}$ at 5.5V ~ 38V
- 4. Able to withstand ESD test of IEC-61000-4-2
- 5. Bi-directional clamping characteristic

APPLICATIONS

- 1. Protection of cellular phones, PDA, High Speed Data Line...etc.
- 2. ESD Protection for components sensitive to IEC 61000-4-2, Provides Circuit Board Transient Voltage Protection for Transistors.
- Protection of Video & Audio Ports.

DIMENSIONS

Figure	Symbol	VZ0603 Series
Ts ↓	L	1.60 ± 0.15 mm
L W Ts T	W	0.80 ± 0.15 mm
	Т	0.90 mm (max.)
Wasin	Ts	0.35 ± 0.15 mm

^{*}Terminal electrode: Ni / Sn electrode



DEVICE RATING AND SPECIFICATIONS

		MAXIMUM RATINGS					SPECIFICATIONS		
5	Max. Continuous Working Voltage		Maximum Non- Repetitive Surge Current	Maximum Non- Repetitive Surge Energy	Max. Claming Voltage at Specified	Nominal Voltage At 1mA (DC) Current		Typical Capacitance	
Part Number			(8/20 μ s)	(10/1000 μ s)	Current (8/20 μ s)		@1KF		
	$V_{M(DC)}$	V _{M(AC)}	I _{TM}	W_{TM}	Vc	V _{N(DC)} Min	V _{N(DC)} Max.	С	
	(V)	(V)	(A)	(J)	(V)	(V)	(V)	(pF)	
VZ0603M050AGT	5.5	4	30	0.1	20 at 1A	8	11	800	
VZ0603M090AGT	9 6		30	0.1	23 at 1A	10.2	13.8	680	
VZ0603M140AGT	14	11	30	0.1	30 at 1A	15.3	20.7	350	
VZ0603M180AGT	18	14	30	0.1	39 at 1A	21.6	26.4	270	
VZ0603M260AGT	26	20	30	0.1	54 at 1A	29.7	36.3	200	
VZ0603M300AGT	30	25	30	0.1	65 at 1A	35.1	42.9	120	
VZ0603M380AGT	38	30	30	0.1	77 at 1A	42.3	51.7	100	

STANDARD TESTING CONDITION

Unless otherwise specified

■ Temperature : 15 ~ 35°C■ Humidity : 25%RH ~ 85%RH

■ Atmospheric pressure: 86kPa ~ 106kPa



SPECIFICATION

1. Electrical Reliability

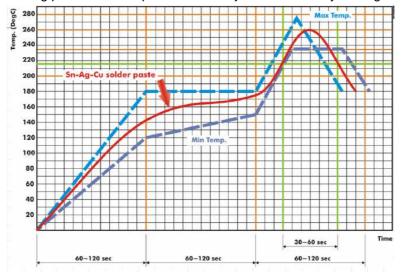
Test item	Test condition / Test method	Specification
High temperature storage	+125±3°C for 1000 hours Measurement to be made after keeping at room temp. for 24 ±2hr	\triangle V at 1mA $<$ 10%
Low temperature storage	-40±3°C for 1000 hours Measurement to be made after keeping at room temp. for 24 ±2h	$\triangle V$ at 1mA $<$ 10%
Humidity storage	40±2°C , 90 ~95%RH for 500 hours Measurement to be made after keeping at room temp. for 24 ±2h	△V at 1mA < 10%
Temperature cycles	Times: 5 cycles Step Temp.($^{\circ}\mathbb{C}$) Time(min.) 1 -55 ± 3 30 ± 3 2 room temp. 2~3 3 +125 ± 3 $^{\circ}\mathbb{C}$ 30 ± 2 4 room temp. 2~3 Measurement to be made after keeping axt room temp. for 24 ± 2 †	△V at 1mA < 10%

2. Mechanical Reliability

Test item	Test condition / Test method	Specification
Solderability	Solder temp.: 230±5°C Immersion time: 2±0.5 sec Immersion and emersion rates: 25mm/s	Min 90% electrode shall be covered with solder.
Resistance to Soldering Heat	Pre-heating: 120~ 150°C , 60 sec Solder temp.: 260±5°C Immersion time: 10±1 sec Measurement to be made after keeping at room temp. for 24 ±2h	△V at 1mA < 10% Disappearance of electrode due to immersion into solder shall not exceed 25% of edges of each electrode.
Adhesive Strength of Termination	Solder chip on PCB and applied 0805/1206 Series: 10N(1Kgf) for 10 sec 0402/0603 Series: 5N(0.5Kgf) for 10 sec Chip varistor	No visible damage
Vibration	Solder chip on PCB. Frequency: 10 Hz~55 Hz~10 Hz (1min) Oscillation amplitude: 1.5 mm Times: 2 hrs in each of three perpendicular direction	No visible damage
Bending Test	The middle part of substrate shall be pressurized by means of the pressurizing rod at a rate of 1mm per second until the deflection becomes 1 mm and then the pressure shall be maintained for 5 sec	No visible damage $\triangle V$ at 1mA $<$ 10%

SOLDERING CONDITION

Typical examples of soldering processes that provide reliable joints without any damage are given in figure below:



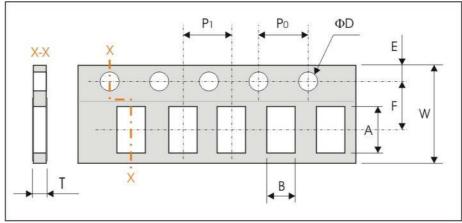
Infrared soldering profile

ORDERING CODE

VZ	0603	M	050	Α	G	Т
Type Code	Chip Size	Style	Rated Voltage	Capacitance Tolerance	Termination	Packing
VZ: Walsin Varistor	0402 0603	M: Multilayer A: Array	050 = 5.5V 070 = 7V 090 = 9V 140 = 14V 180 = 18V	A: Standard	G: Green Material	T: Reeled B: Bulk

PACKAGING

Paper Tape specifications (unit :mm) and Packaging quantity

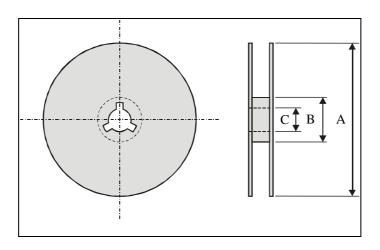


Label	А	В	E	F	ΦD
VZ0603 Series	1.80 ± 0.05	0.95 ± 0.05	1.75 ± 0.05	3.50 ± 0.05	1.55 ± 0.05

Label	P0	P1	Т	W	Quantity/Reel
VZ0603 Series	4.00 ± 0.10	2.00 ± 0.10	0.87 ± 0.05	8.00 ± 0.20	4Kpcs

[•] Tape Material : Paper tape.

Reel dimensions



Index	Α	В	С
Dimension (mm)	Φ178	Ф60.0	Ф13.5



CAUTION OF HANDLING

Limitation of Applications

Please contact us before using our products for the applications listed below which require especially high reliability for the prevention of defects, which might directly cause damage to the third party's life, body or property.

- (1) Aircraft equipment
- (2) Aerospace equipment
- (3) Undersea equipment
- (4) Medical equipment
- (5) Traffic signal equipment
- (6) Applications of similar complexity and /or reliability requirements to the applications listed in the above.

Storage condition

- (1) Products should be used in 6 months from the day of WALSIN outgoing inspection, which can be confirmed.
- (2) Storage environment condition.
 - Products should be storage in the warehouse on the following conditions.

■ Temperature : -10 to +40°C

Humidity : 30 to 70% relative humidity

- Don't keep products in corrosive gases such as sulfur. Chlorine gas or acid or it may cause oxidization of electrode, resulting in poor solderability.
- Products should be storage on the palette for the prevention of the influence from humidity, dust and son on.
- Products should be storage in the warehouse without heat shock, vibration, direct sunlight and so on.
- Products should be storage under the airtight packaged condition.